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PATENT
62230-000002/US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Heung-Kyu KWON et al.

Serial No.: 09/464,322

Group: 2815

Filed: December 15, 1999

Examiner: Chris C. Chu

For: SEMICONDUCTOR CHIP PACKAGE AND METHOD OF FABRICATING
THE SAME

RULE 116 AMENDMENT

Honorable Commissioner for Patents
Washington, D.C. 20231

February 19, 2003

Dear Sir:

Responsive to the final Office Action dated November 19, 2002 please enter the following
amendments and comments.

RECEIVED
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